



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|-----------------|
| Chip Size | 2220 |
| L | 5.7mm +/-0.4mm |
| W | 5mm +/-0.4mm |
| T | 1.6mm +/-0.20mm |
| B | 0.6mm +/-0.35mm |

Packaging Specifications

| | |
|--------------------|--------------|
| Packaging | Waffle, Tray |
| Packaging Quantity | 20 |

General Information

| | |
|------------------|-------------------------------------------------------------------|
| Series | SMD Indust COG HVHT200C |
| Style | SMD Chip |
| Description | SMD, MLCC, High Temperature, Ultra-Stable, Low Loss |
| Features | High Temp, Ultra-Stable, Low Loss |
| RoHS | Yes |
| Termination | Gold |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 190 mg |
| Miscellaneous | Moisture Sensitive Packaging. Gold (Au) 1.97 - 11.8 micro inches. |
| Shelf Life | 26 Weeks |
| MSL | 1 |

Specifications

| | |
|--------------------------------------------------------------------|------------------------|
| Capacitance | 2000 pF |
| Measurement Condition | 1kHz 1.0Vrms |
| Capacitance Tolerance | 10% |
| Voltage DC | 2000 VDC |
| Dielectric Withstanding Voltage | 2400 VDC |
| Temperature Range | -55/+200°C |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor | 0.1% 1kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |